

Abstract of the Disclosure

A method for electrolytic copper plating using an electrolytic copper plating solution including a compound containing a structure of $-X-S-Y-$, wherein X and Y are independently chosen from hydrogen atom, carbon atom, sulfur atom, nitrogen atom, and oxygen atom, and X and Y may be the same only when they are a carbon atom, and by contacting the electrolytic copper plating solution with ozone is disclosed.